

PROCESS FOR MANUFACTURING A WIRING BOARD

ABSTRACT OF THE DISCLOSURE

A resin plate having wiring pattern recesses and via through holes is made. All of the surfaces of the resin plate including inner walls of ~~said~~ the wiring pattern recesses and via through holes are coated with a metal film. An electroplating is applied using the metal film as a power-supply layer to fill a plated metal into the wiring pattern recesses and via through holes. The metal film formed on the resin plate except for the inner walls of the wiring pattern recesses and via through holes is removed, so that wiring pattern and via are exposed on a surface the same as that of the resin plate.